

Green Products

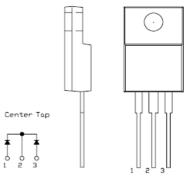
MBRF40150CTL SCHOTTKY RECTIFIER

Applications:

- Switching power supply
- Converters
- Free-Wheeling diodes
- Reverse battery protection

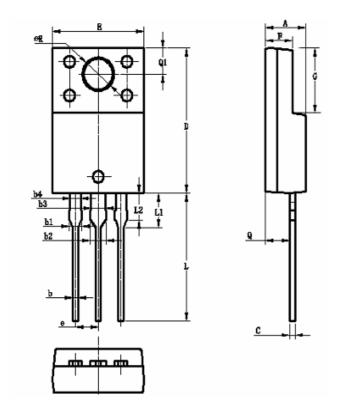
Features:

- 150°C T_J operation
- Center tap configuration
- Low forward voltage drop
- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- High frequency operation
- Guard ring for enhanced ruggedness and long term reliability
- This is a Pb Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request



OUTLINE DRAWING

Mechanical Dimensions: In mm / Inches



	OPTION 1(CJ)		OPTIO	N 2(HD)
Dim	Min	Max	Min	Max
Α	4.4	4.6	4.30	4.70
b	0.6T	ΥP	0.50	0.75
b1	1.3T	ΥP	1.30	1.40
b2	1.7T	ΥP	1.70	1.80
b3	1.6T	ΥP	1.50	1.75
b4	1.2T	ΥP	1.10	1.35
С	0.60	ГҮР	0.50	0.75
D	14.8	15.1	14.80	15.20
E	10.06	10.26	9.96	10.36
е	2.55TYP		2.54TYP	
F	2.9	3.1	2.80	3.20
G	6.5	6.9	6.50	6.90
L	12.7	13.7	13.2	12.8
L1	3.4	3.8	3.60	4.00
L2	2.6	3.0	-	-
Q	2.5	2.9	2.50	2.90
Q1	2.5	2.9	2.70	REF
ØR	3.5REF		3.50	REF

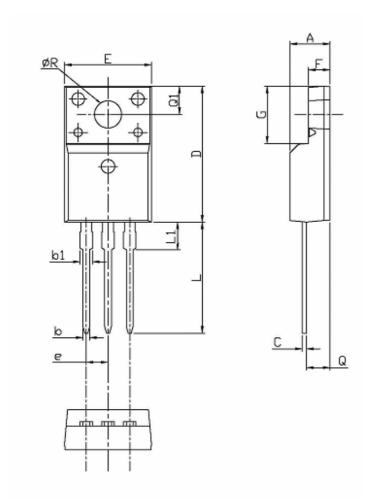
[•] Weiqi Street, Airport Development Zone, Jiangning District, Nanjing, China 211113 🗏 (86) 25-87123907 •

[•] FAX (86) 25-87123900 • World Wide Web Site - http://www.sangdest.com.cn • E-Mail Address - sales@ sangdest.com.cn •





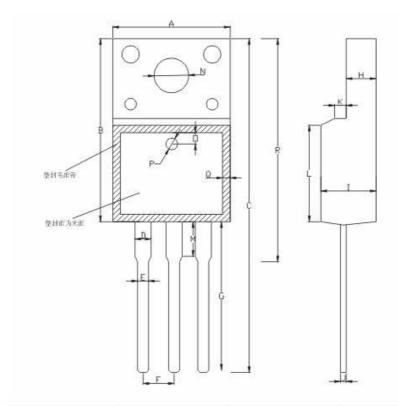
Green Products



	OPTION 3		OPTION 4		
Dim	Min	Max	Min	Max	
Α	4.53	4.93	4.50	4.90	
b	0.71	0.91	0.70	0.90	
b1	1.15	1.39	1.33	1.47	
С	0.36	0.53	0.45	0.60	
D	15.67	16.07	15.67	16.07	
E	9.96	10.36	9.96	10.36	
е	2.547	ГҮР	2.54 BSC		
F	2.34	2.76	2.34	2.74	
G	6.50	6.90	6.48	6.88	
L	12.37	12.77	12.78	13.18	
L1	2.23	2.63	3.03	3.43	
Q	2.56	2.96	2.56	2.96	
Q1	3.10	3.50	3.10	3.50	
ØR	2.98	3.38	3.08	3.28	



Green Products



A:10.20	± 0.50	B:15.90	±0.50	C:29.00	± 1.00	D:1.24	± 0.10
E:0.80	± 0.10	F:2.54	± 0.10	G:13.10	$\pm 1,0$	H:2.55	± 0.05
I:4.70	±0.05	J:0.50	± 0.05	K:1.20	± 0.20	L:8.00	±0.50
M:3.00	±0.50	N:3.20	± 0.20	O:1,25	± 0.05	P:1.5	± 0.05
Q:1.0	±0.20	R:19.2	±1.0				

OPTION 5(SR)

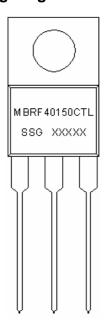
ITO-220AB





Green Products

Marking Diagram:



Where XXXXX is YYWWL

MBR = Device Type F = Package type

40 = Forward Current (40A) 150 = Reverse Voltage (150V)

CTL = Configuration

 SSG
 = SSG

 YY
 = Year

 WW
 = Week

 L
 = Lot Number

Cautions: Molding resin

Epoxy resin UL:94V-0

Ordering Information:

Device	Package	Shipping
MDDE40450CTI	ITO-220AB	FOnce / tube
MBRF40150CTL	(Pb-Free)	50pcs / tube

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification.

Maximum Ratings:

Characteristics	Symbol	Condition	Max.	Units
Peak Inverse Voltage	V_{RWM}	-	150	V
Max. Average Forward Current	I _{F(AV)}	50% duty cycle @T _C =133℃, rectangular wave form	20(per leg) 40(Per device)	Α
Max. Peak One Cycle Non- Repetitive Surge Current (per leg)	I _{FSM}	8.3 ms, half Sine pulse	432	Α

[•] Weiqi Street, Airport Development Zone, Jiangning District, Nanjing, China 211113 🗏 (86) 25-87123907 •

[•] FAX (86) 25-87123900 • World Wide Web Site - http://www.sangdest.com.cn • E-Mail Address - sales@ sangdest.com.cn •





Green Products

Electrical Characteristics:

Characteristics	Symbol	Condition	Max.	Units
Max. Forward Voltage Drop	V_{F1}	@ 20A, Pulse, T _J = 25 °C	0.95	V
(per leg)*	V_{F2}	@ 20 A, Pulse, T _J = 125 °C	0.80	V
Max. Reverse Current at DC	I _{R1}	@V _R = rated V _R	1.0	mA
condition (per leg)		T _J = 25 °C		
Max. Reverse Current (per	I _{R2}	$@V_R = rated V_R$	15.0	mA
leg)*		T _J = 125 °C		
Non-Repetitive Avalanche	Eas	$T_J = 25 ^{\circ} C$, $I_{AS} = 2 A$,	2	mJ
Energy		L = 1mH		
Max. Junction Capacitance	C _T	$@V_R = 5V, T_C = 25 ^{\circ}C$	900	pF
(per leg)		$f_{SIG} = 1MHz$		
Typical Series Inductance	L _S	Measured lead to lead 5 mm from	8.0	nΗ
(per leg)		package body		
Max. Voltage Rate of Change	dv/dt	-	10,000	V/μs
RSM Isolation Voltage	V_{ISO}	Clip mounting, the epoxy body	4500	V
(t = 1.0 second, R. H. < =30%,		away from the heatsink edge by		
$T_A = 25 ^{\circ}C$		more than 0.110" along the lead		
		direction.		
		Clip mounting, the epoxy body is	3500	
		inside the heatsink.		
		Screw mounting, the epoxy body	1500	
		is inside the heatsink.		

^{*} Pulse Width < 300 μ s, Duty Cycle <2%

Thermal-Mechanical Specifications:

Characteristics	Symbol	Condition	Specification	Units
Max. Junction Temperature	T_J	-	-55 to +150	Ô
Max. Storage Temperature	T _{stg}	-	-55 to +150	°C
Maximum Thermal Resistance Junction to Case (per leg)	R _{θJC}	DC operation	3.5	°C/W
Approximate Weight	wt	-	1.9	g
Case Style		ITO-220AB		

[•] Weiqi Street, Airport Development Zone, Jiangning District, Nanjing, China 211113 🗏 (86) 25-87123907 •

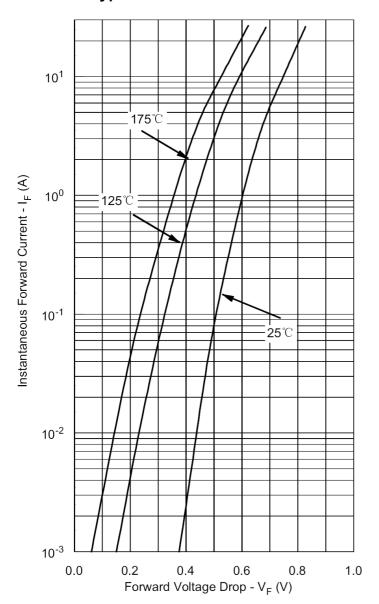
[•] FAX (86) 25-87123900 • World Wide Web Site - http://www.sangdest.com.cn • E-Mail Address - sales@ sangdest.com.cn •



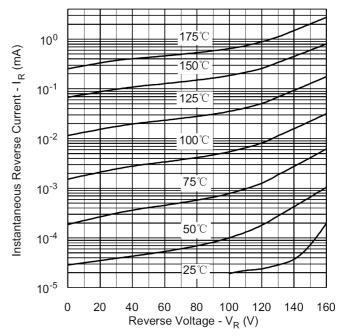


Green Products

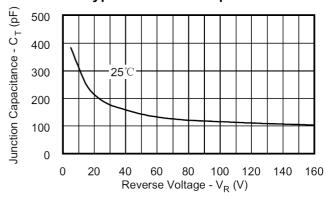
Typical Forward Characteristics



Typical Reverse Characteristics







[•] Weiqi Street, Airport Development Zone, Jiangning District, Nanjing, China 211113 🗏 (86) 25-87123907 •

[•] FAX (86) 25-87123900 • World Wide Web Site - http://www.sangdest.com.cn • E-Mail Address - sales@ sangdest.com.cn •



MBRF40150CTL

Technical Data Data Sheet N0860, Rev. A **Green Products**

DISCLAIMER:

- 1- The information given herein, including the specifications and dimensions, is subject to change without prior notice to improve product characteristics. Before ordering, purchasers are advised to contact the SMC Sangdest Microelectronics (Nanjing) Co., Ltd sales department for the latest version of the datasheet(s).
- 2- In cases where extremely high reliability is required (such as use in nuclear power control, aerospace and aviation, traffic equipment, medical equipment, and safety equipment), safety should be ensured by using semiconductor devices that feature assured safety or by means of users' fail-safe precautions or other arrangement.
- 3- In no event shall SMC Sangdest Microelectronics (Nanjing) Co., Ltd be liable for any damages that may result from an accident or any other cause during operation of the user's units according to the datasheet(s). SMC Sangdest Microelectronics (Nanjing) Co., Ltd assumes no responsibility for any intellectual property claims or any other problems that may result from applications of information, products or circuits described in the datasheets.
- 4- In no event shall SMC Sangdest Microelectronics (Nanjing) Co., Ltd be liable for any failure in a semiconductor device or any secondary damage resulting from use at a value exceeding the absolute maximum rating.
- 5- No license is granted by the datasheet(s) under any patents or other rights of any third party or SMC Sangdest Microelectronics (Nanjing) Co., Ltd.
- 6- The datasheet(s) may not be reproduced or duplicated, in any form, in whole or part, without the expressed written permission of SMC Sangdest Microelectronics (Nanjing) Co., Ltd.
- 7- The products (technologies) described in the datasheet(s) are not to be provided to any party whose purpose in their application will hinder maintenance of international peace and safety nor are they to be applied to that purpose by their direct purchasers or any third party. When exporting these products (technologies), the necessary procedures are to be taken in accordance with related laws and regulations..